

Programme Review Day
Brussels, 28/29 November 2012

Working towards Mass
Manufactured, Low Cost and
Robust SOFC stacks

MMLCR=SOFC

Contract number FCH JU 278525

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Project description

- duration 01.01.2012 – 30.06.2014
- total budget 4.494.396 €, funding 2.067.975 € (46%)
- addresses the improvement of thermo-mechanical robustness of lightweight stack designs and their automated manufacturing

The consortium consists of 8 partners:

University of Birmingham (coordinator)

Forschungszentrum Jülich

BORIT

Rohwedder Micro Assembly GmbH

Bekaert

Turbocoating

CSIC

SOFCPower

amendment for coordinator change from JUELICH to B'ham still ongoing

Problems addressed

- new architecture with reduced thermal stresses
- improvements of performance and reliability:
robustness to cycling and transient operating conditions.
- simplification of manufacturing
- improved quality assurance by automated assembly
- cost efficient design

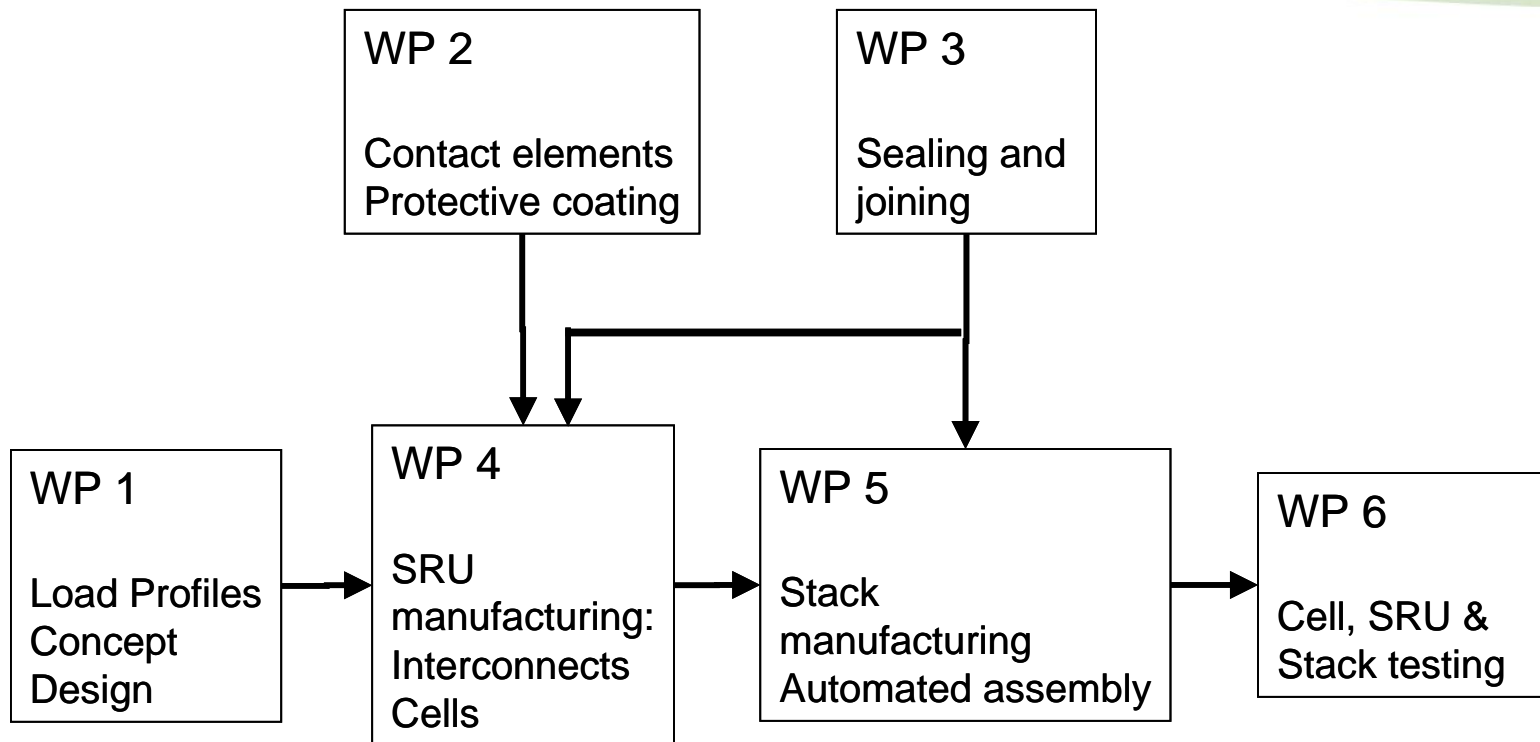
Project goals

- reduce thermal stress in modified Juelich CS IV design
- implement improved glass sealants and sealant processing
- optimise application of protective coating prior to and after forming step
- design and optimise automated manufacturing process

Outcome:

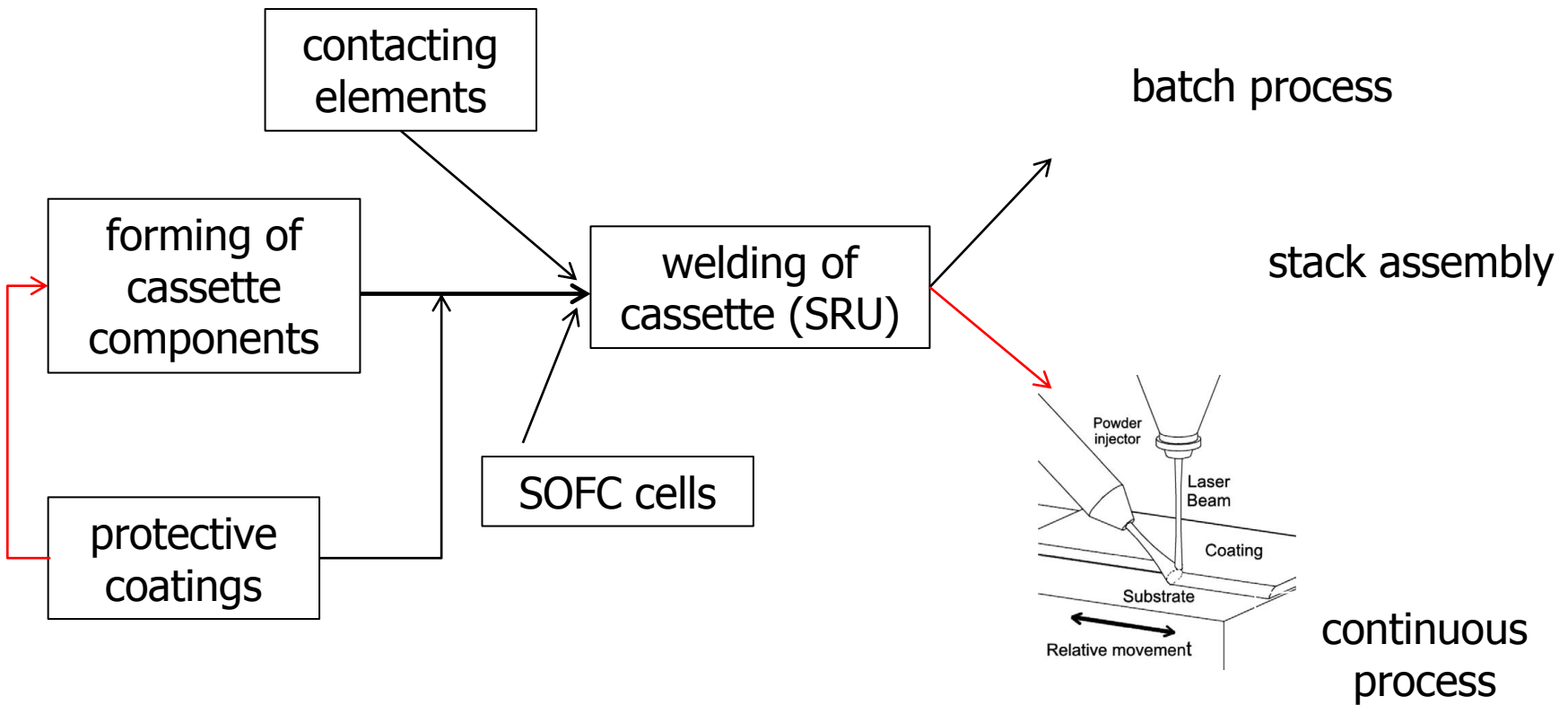
- lightweight stack for transport or stationary applications
- reduced cost, improved robustness and quality (reproducibility)
- mass-manufacturing compatible processes and assembly machines

Project Approach



Project Approach (2)

— alternative routes



Project results: APU Benchmarking



Pony Pack

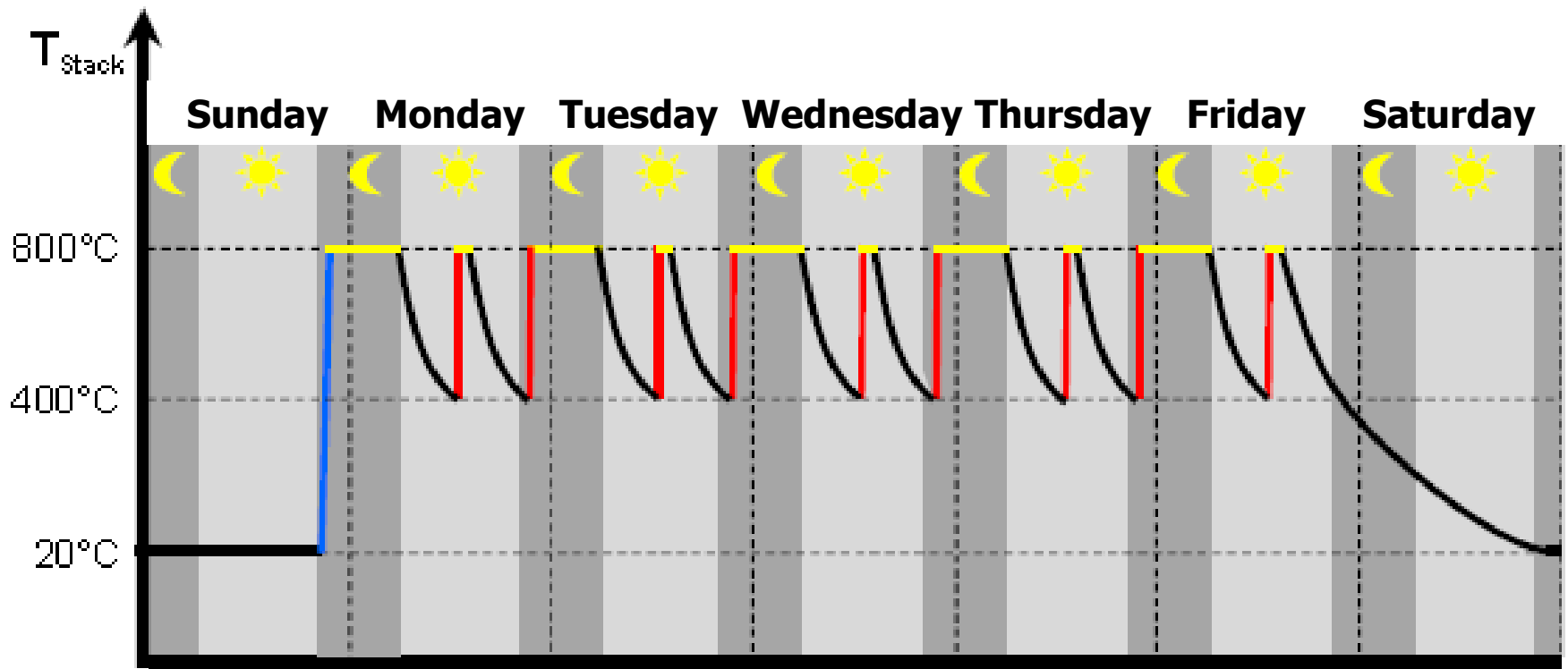


Diesel ICE APU 5 kW	
Cost (\$)	7000-9000
Max. efficiency (%)	30
Volume (L)	150-400
Weight (kg)	180-230
Durability (h)	>4000
Start-up time	<2 min

1400 – 1800 US\$/kW

Project results: APU Benchmarking (2)

Definition of 'Cycling'



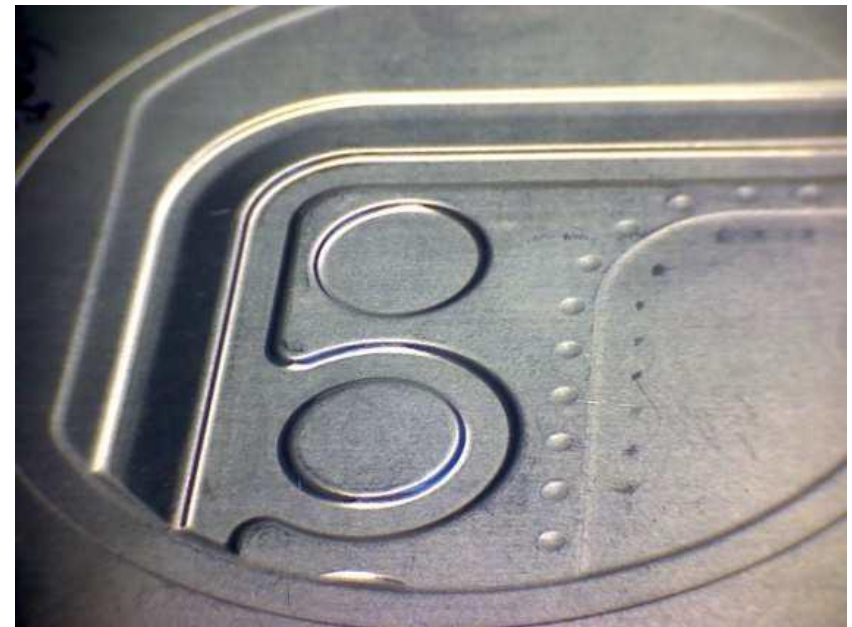
US 'Idling' case

Project results: Steel Forming

First forming tests using

- CroFer 22 APU,
- CroFer 22 H,
- Hitachi ZMG232L,
- Sandvik Sanergy HT

Geometry: CS IV (Juelich design)



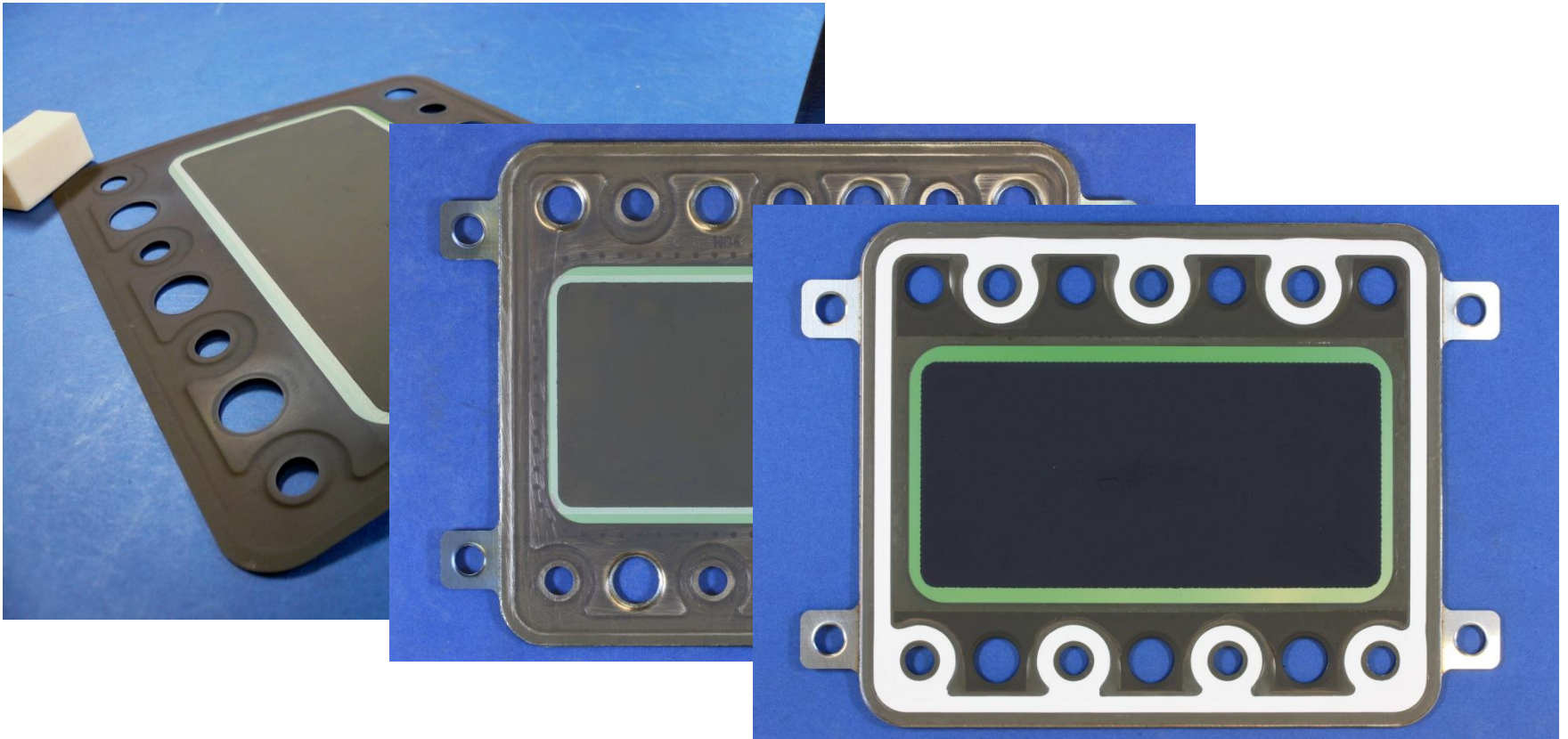
Project results: Steel Forming (2)

Design "1.0":
testing of
suitability of
materials &
components from
all partners



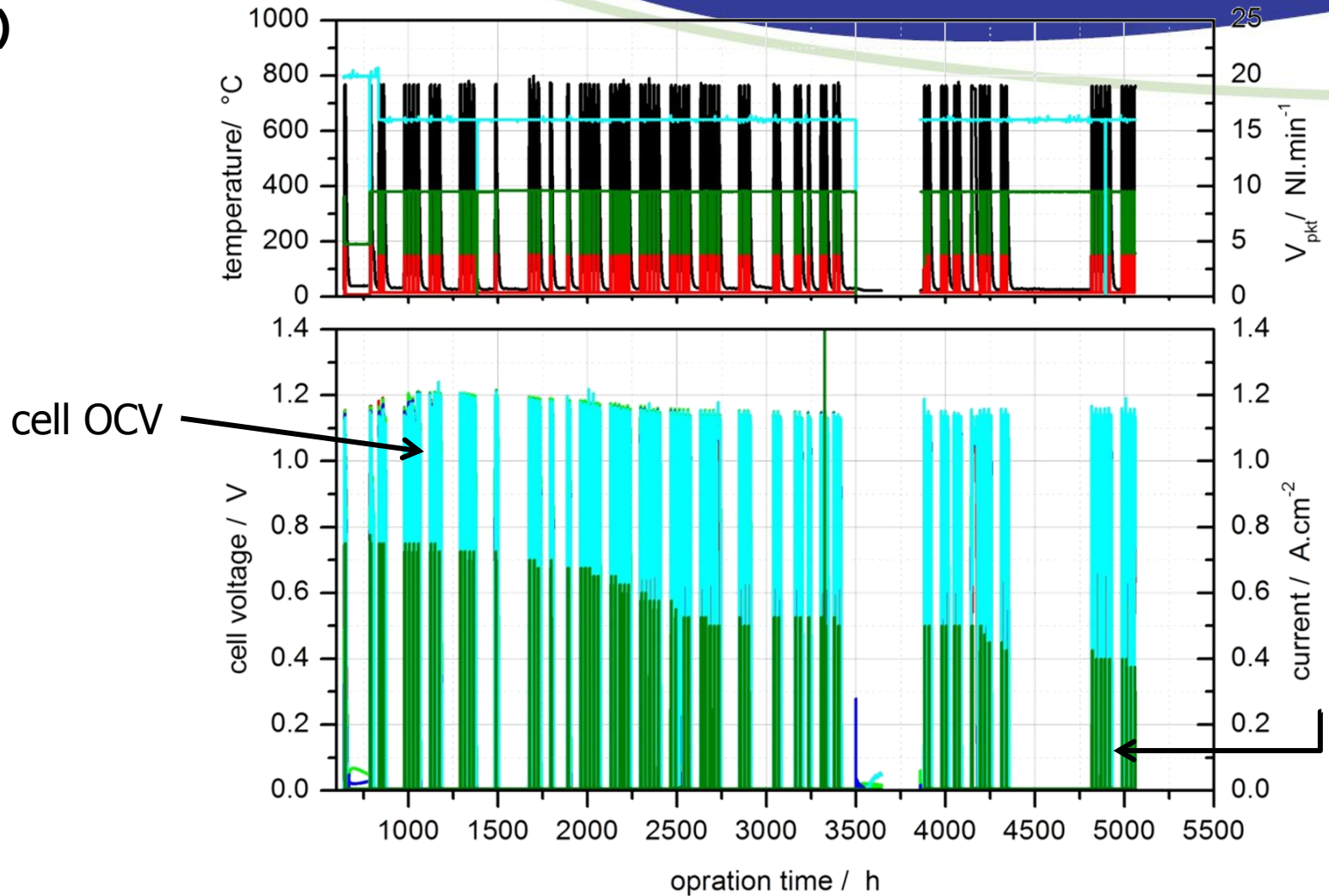
Project results: Cassette Manufacturing

Half-automated manufacturing of gas-tight cassettes, Design 1.0 (CS IV)



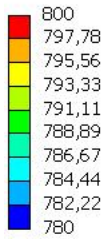
Project results: Stack Testing (Benchmarking)

Reference stack testing (CS II)



Modelling of thermo-mechanical stress

Temperature distribution in two alternative designs

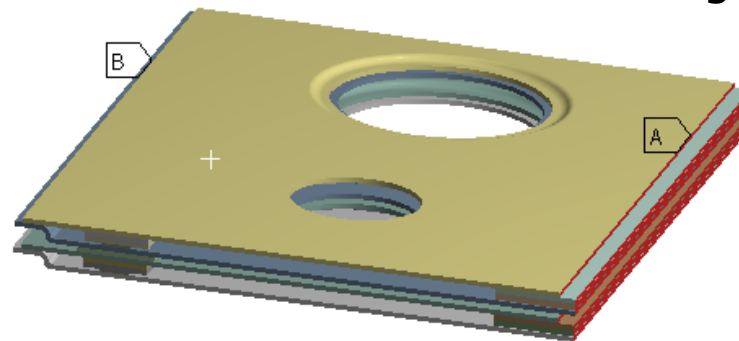


swage design CS IV
(Design 1.0)

A Temperature: 800, °C
B Temperature 2: 780, °C

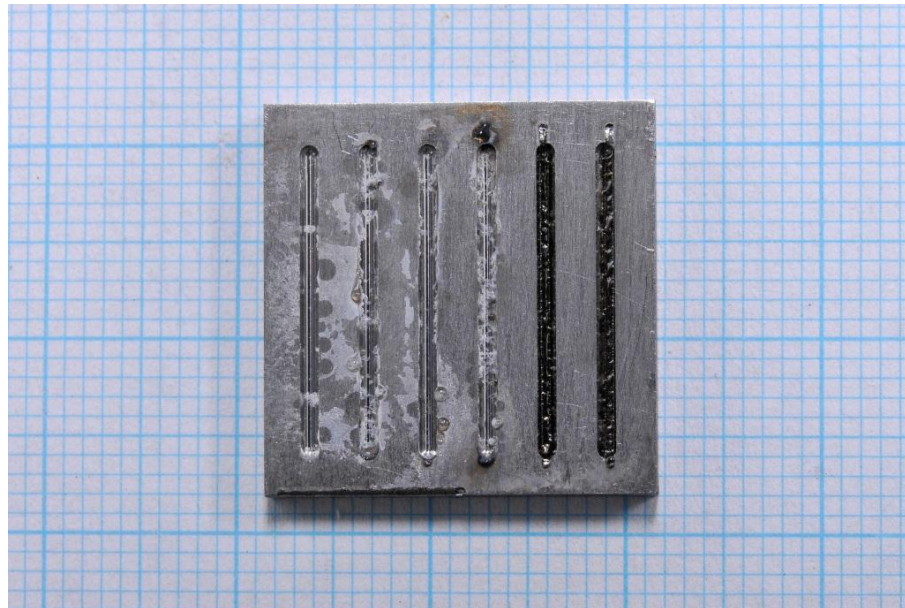
Design 1.1

Boundary Conditions →



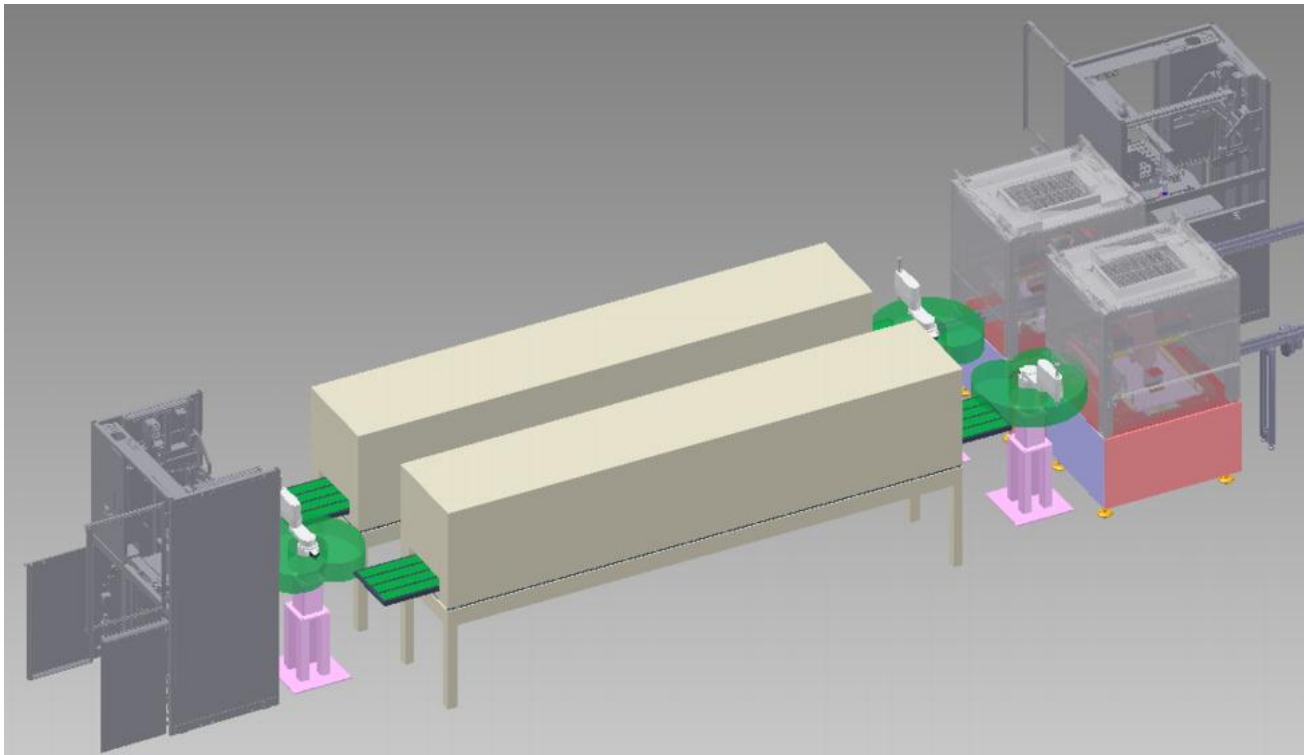
Critical Benchmarking of Glass Welding Procedures

- laser supported glass welding is extremely interesting under the aspects of automated manufacturing
- process is, though, very critical
- work has begun on evaluating potential for optimising operating parameters



Manufacturing Equipment Design

- first feasibility studies for manufacturing and assembly process



- “novel architectures for cell and stacks leading to step change improvements over existing technology in terms of performance, endurance, robustness, durability and cost “
- “Similarities exist between the base technology and requirements of the fuel cell technologies in this Application Area and those for on-board power generation (e.g. APU)”
- project in principle addresses stack architectures suitable both for stationary and transport applications
- besides robustness to thermal cycling also addresses cost reduction and increase of quality through automated manufacturing

commercialisation of

- stack technology through consortium partner SOFCpower
- coating solutions through consortium partner Turbocoating
- glass sealants via FZJ and CSIC activities
- manufacturing solutions through consortium partners BORIT and Rohwedder (both with respect to process control/machines/process development, and component manufacturing)

possible interaction with new project (currently in negotiation)

SCORED 2:0 (coating of SOFC interconnects)



Thank You for your Attention !